

# HD74LS10

## Triple 3-Input Positive NAND Gates

REJ03D0396-0200  
Rev.2.00  
Feb.18.2005

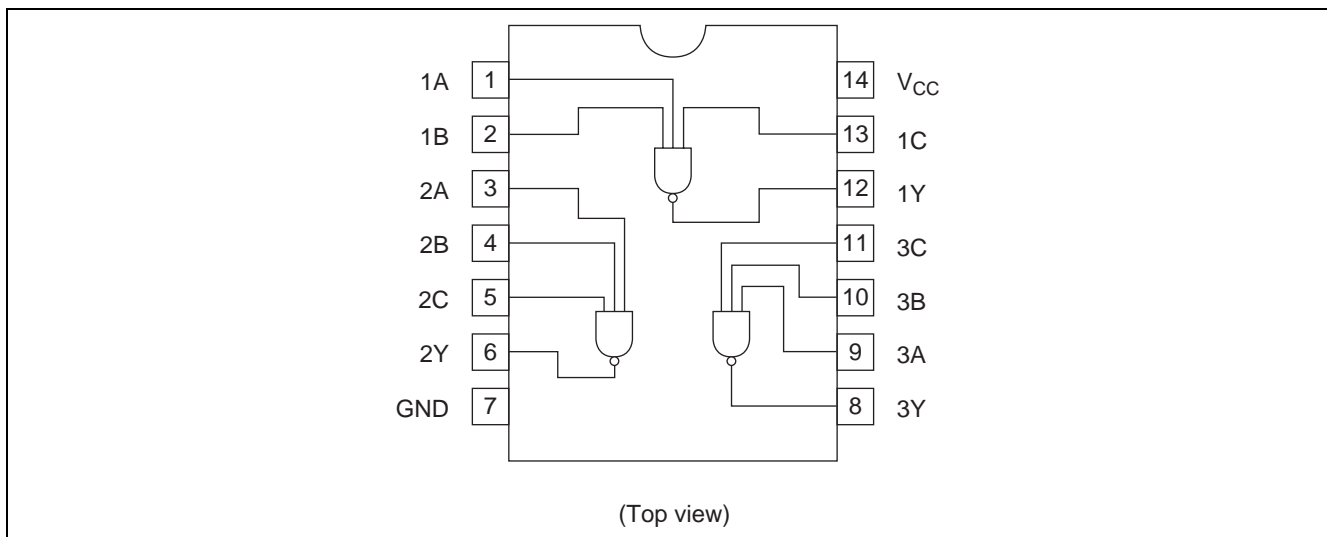
### Features

- Ordering Information

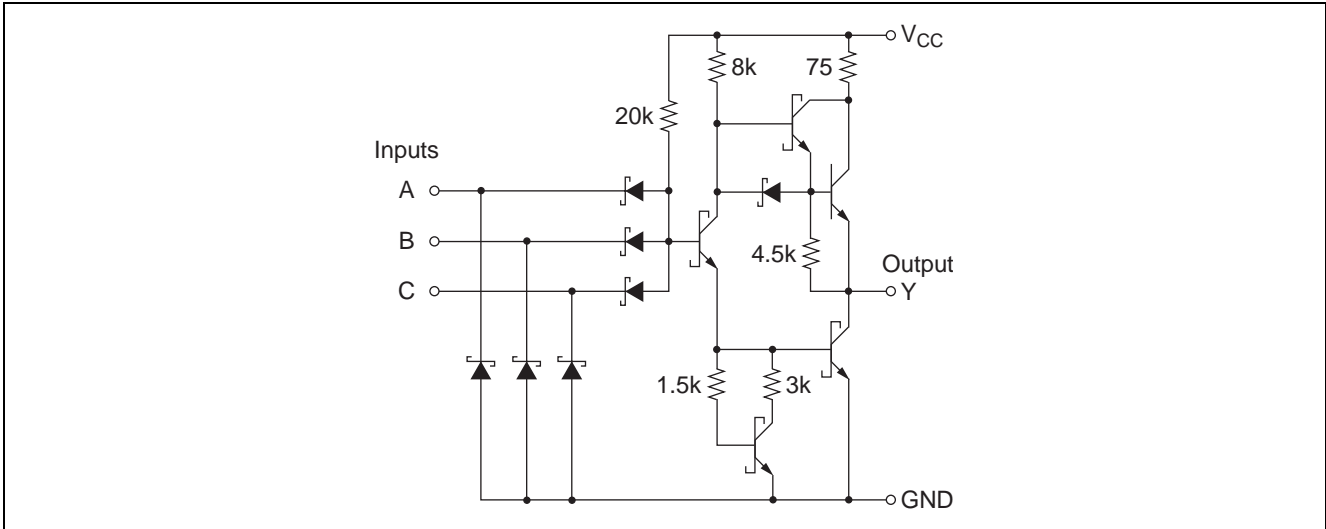
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS10P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS10FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS10RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

### Pin Arrangement



Circuit Schematic (1/3)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	$V_{CC}$ <sup>Note</sup>	7	V
Input voltage	$V_{IN}$	7	V
Power dissipation	$P_T$	400	mW
Storage temperature	$T_{stg}$	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$	4.75	5.00	5.25	V
Output current	$I_{OH}$	—	—	-400	μA
	$I_{OL}$	—	—	8	mA
Operating temperature	$T_{opr}$	-20	25	75	°C

**Electrical Characteristics**

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V <sub>IH</sub>	2.0	—	—	V	
	V <sub>IL</sub>	—	—	0.8	V	
Output voltage	V <sub>OH</sub>	2.7	—	—	V	V <sub>CC</sub> = 4.75 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -400 μA
	V <sub>OL</sub>	—	—	0.5	V	V <sub>CC</sub> = 4.75 V, V <sub>IH</sub> = 2 V
		—	—	0.4		
Input current	I <sub>IH</sub>	—	—	20	μA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 2.7 V
	I <sub>IL</sub>	—	—	-0.4	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 0.4 V
	I <sub>I</sub>	—	—	0.1	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 7 V
Short-circuit output current	I <sub>OS</sub>	-20	—	-100	mA	V <sub>CC</sub> = 5.25 V
Supply current	I <sub>CCH</sub>	—	0.6	1.2	mA	V <sub>CC</sub> = 5.25 V
	I <sub>CCL</sub>	—	1.8	3.3		
Input clamp voltage	V <sub>IK</sub>	—	—	-1.5	V	V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = -18 mA

Note: \* V<sub>CC</sub> = 5 V, Ta = 25°C

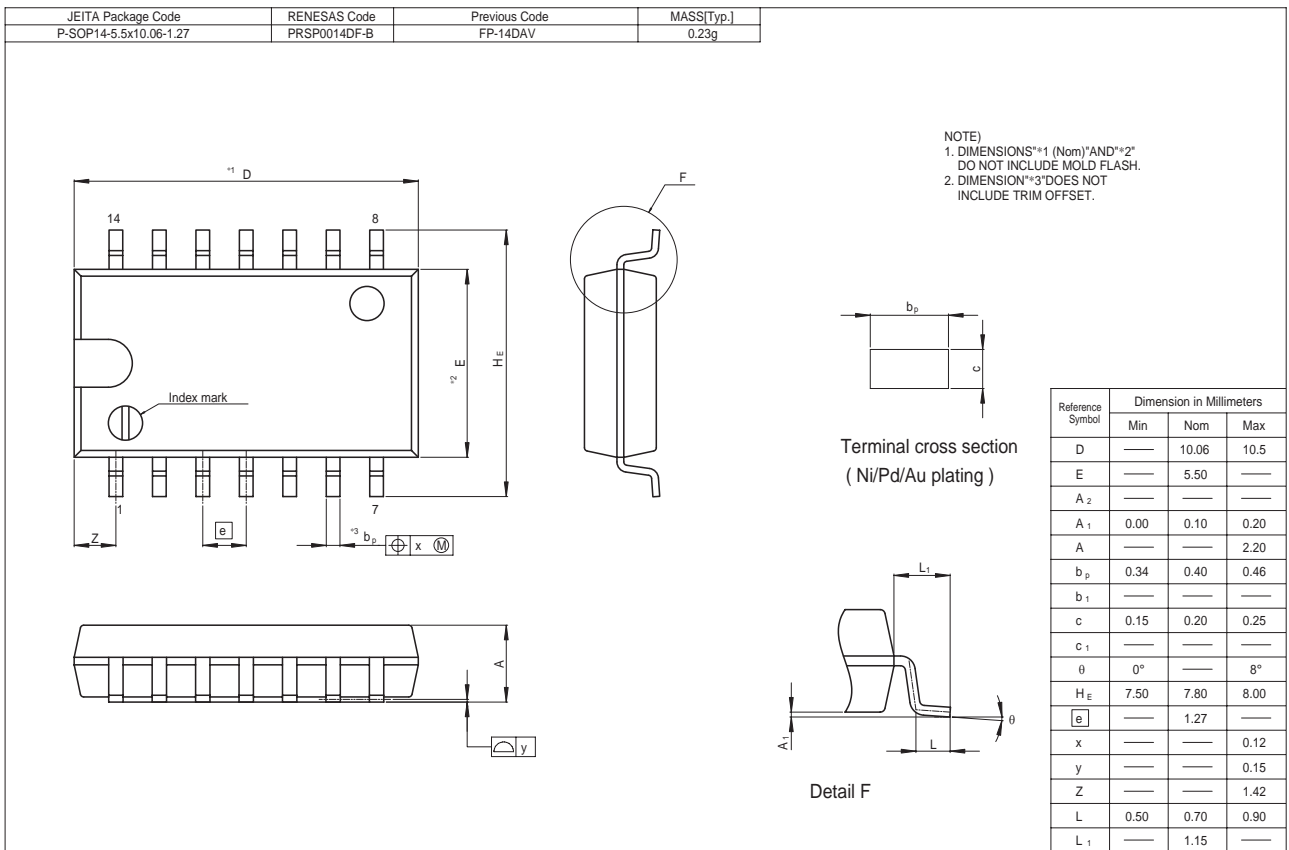
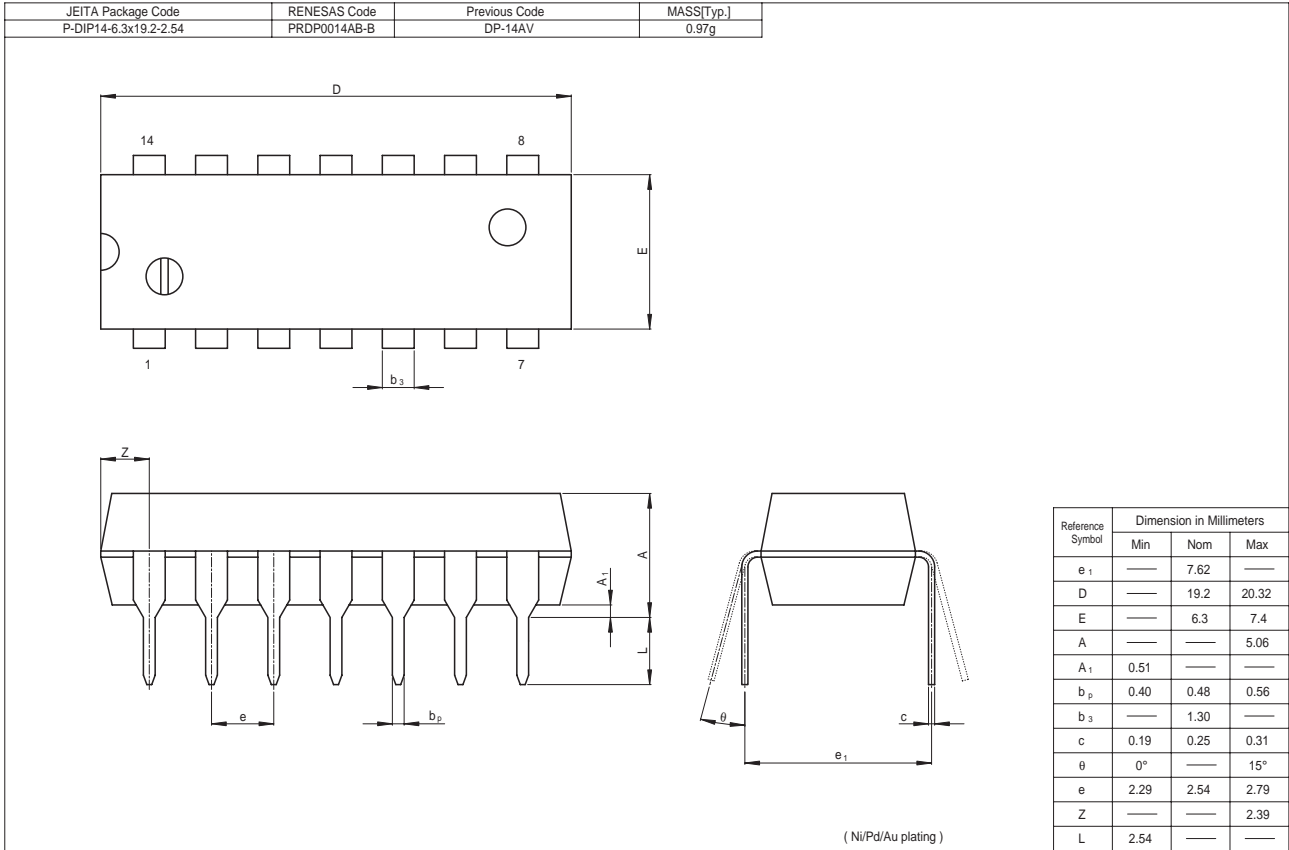
**Switching Characteristics**

(V<sub>CC</sub> = 5 V, Ta = 25°C)

Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t <sub>PLH</sub>	—	9	15	ns	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ
	t <sub>PHL</sub>	—	10	15	ns	

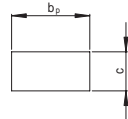
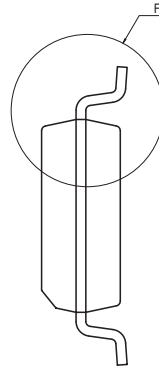
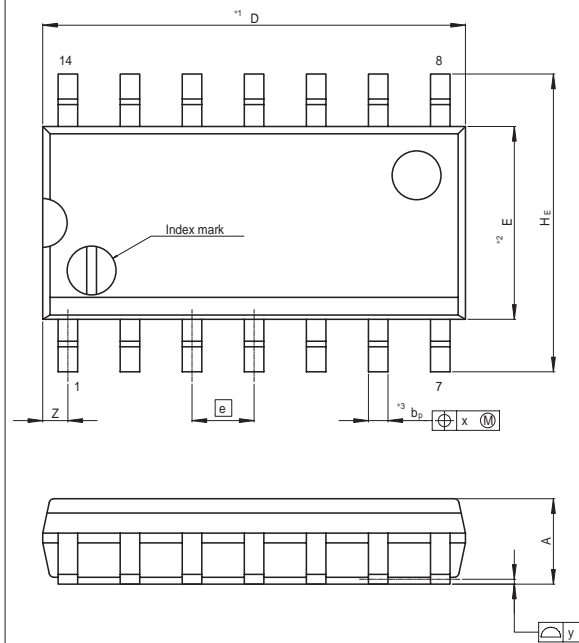
Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

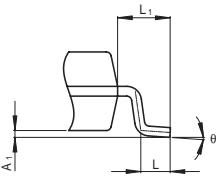


# HD74LS10

JEITA Package Code P-SOP14-3.95x8.65-1.27	RENESAS Code PRSP0014DE-A	Previous Code FP-14DNV	MASS[Typ.] 0.13g
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Terminal cross section (Ni/Pd/Au plating)



Detail F

NOTE)  
1. DIMENSIONS\*1 (Nom)\*AND\*2\*  
DO NOT INCLUDE MOLD FLASH.  
2. DIMENSION\*3\*DOES NOT  
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.10	0.14	0.25
A	—	—	1.75
b <sub>p</sub>	0.34	0.40	0.46
b <sub>1</sub>	—	—	—
c	0.15	0.20	0.25
c <sub>1</sub>	—	—	—
$\theta$	0°	—	8°
H <sub>E</sub>	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L <sub>1</sub>	—	1.08	—

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